



Realize Your Product Promise®

2019 R1

C A P A B I L I T I E S

CONTENT

STRUCTURES

Geometric Idealization.....	3
Modeling Capabilities	3
Materials.....	4
Composite Materials	4
Structural Solver Capabilities	5
Topology Optimization	5
Multi Analysis	5
Vibrations	6
Nonlinear Transient Dynamics.....	6
Explicit Dynamics.....	7
Durability.....	7
Wave Hydrodynamics.....	8
Thermal.....	8
Additional Physics.....	8
Optimization	9
Miscellaneous and Usability.....	9
HPC - Structures	9

FLUIDS

General Solver Capabilities	10
Single Phase Non-Reacting Flows.....	10
Heat Transfer.....	11
Particles Flows (Multiphase).....	11
Free Surface Flows (Multiphase)	11
Dispersed Multiphase Flows (Multiphase).....	12
Reacting Flows	12
Turbomachinery	13
In-Flight Icing	13
Optimization	14
High Rheology Material.....	14
HPC - Fluids.....	14
Pre and Post Processing.....	14
Multiphysics.....	15

Fluid-Structure Interacton.....	15
Electro-Thermal Interaction.....	15
Other Coupled Interactions	15
Ease of Use and Productivity.....	15

ELECTRONICS

Low Frequency Electromagnetics	16
Magnetic Transient.....	16
Advanced Magnetic Modeling.....	16
High Frequency Electromagnetics	17
Power and Signal Integrity Board Simulation Capabilities	19
RLCG Parasitic Extraction.....	20
Electronics Cooling.....	20
HPC for Electronics.....	21

SYSTEMS MODELING - ELECTRONIC PRODUCTS

System Modeling for Power Electronics.....	21
System Modeling for RF/Microwave...	21
System Modeling for SI/PI.....	22

MULTIPHYSICS

Platform Technologies.....	22
Electro-Thermal Interaction.....	22
Miscellaneous	22

SYSTEMS & EMBEDDED SOFTWARE

System Simulation, Validation and Digital Twins.....	23
Functional Safety Analysis.....	23
Model-based Systems Engineering....	24

Embedded Control Software Development.....	24
Man-Machine Interface Software.....	25

VRXPERIENCE

Photometry	25
Human Vision.....	25
Optical Sensors	25
Head-up Display	25
Driving	26
Rendering / Simu	26
Headlamp Simulation.....	26
Tracking	26
Distributed Rendering.....	26
Experience	27
Engine / Solver Embedded or Interface	27
Acoustics Sounds	27

GEOMETRY

DESIGN TOOLS

Structural.....	29
Fluid.....	29
Thermal.....	29
Electromagnetics.....	30
Multiphysics.....	30
Design & Concept Modeling.....	30
Manufacturing.....	30
3D Printing.....	31
Reverse Engineering	31
Interfaces and Add-Ons.....	31

ADDITIVE SOLUTIONS

Topology and Lattice Optimization .	32
Geometry and STL File Handling.....	32
Workbench Additive.....	32
Additive Print	33
Additive Science	33

OPTICAL

Photometry.....	34
Human Vision.....	34
Wavelength Range.....	34
Optical Design	34
Optical Sensors.....	34
Head-Up Display	35
Manufacturing Variation.....	35
Solver	35
Add-On Features	35

STRUCTURES

	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM		
Geometric Idealization								
Spring	•	•	▲	•	•	•		
Mass	•	•	•	•	•	•		
Damper	•	•		•	•			
Spar	•	•	•					
Beam	•	•	•	•	•			
Pipe/Elbow	•	•	•					
Shell - Thin	•	•	•	•	•	•		
Layered Shell - Thin (Composite)	•	•		•	•			
Shell - Thick (Solid Shell)	•	•	•					
Layered Shell - Thick (Solid Shell) (Composite)	•	•						
2D Plane / Axisymmetric	•	•	•	•	•			
3D Solids	•	•	•	•	•	•		
Layered 3D Solids (Composite)	•	•						
Infinite Domain	•	•	•	•	•			
2.5D	•	•						
Reinforced	•	•		•	•			
ROM	•							
Substructuring / Matrix	•							
Modeling Capabilities								
Contact - Linear	•	•	•	•	•	•		
Contact - Nonlinear	•	•	•	•	•	•		
Joints	•	•	•	•	•	•		
Spot Welds	•	•	•	•	•			
Element Birth and Death	•	•						
Gasket Elements	•							
Rezoning and Adaptive Remeshing	•			•	•			

STRUCTURES

	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM		
Materials								
Basic Linear Materials (Linear, Anisotropic, Temperature Dependent)	•	•	•	•	•	•		
Basic Nonlinear Materials (Hyper, Plasticity, Rate Independent, Isotropic, Concrete)	•	•	▲	•	•	▲		
Advanced Nonlinear Materials (Rate dependent, Anisotropic, Damage Models, Geomechanics Materials, Multiphysics)	•			•	•			
Field Dependent	•	•						
Reactive Materials	•			•				
Fracture Mechanics and Crack Growth	•							
Material Designer	•							
Composite Materials								
Material Definitions	•	•		•	•			
Layers Definitions	•	▲		•	•			
Interface Plies	•							
Advanced Modeling Features	•							
Variable Material Data	•							
Solid Extrusion	•							
Lay-up Mapping	•							
Draping	•							
Lay-up exchange interfaces	•							
Advanced Failure Criteria Library	•							
First-ply Failure	•	•						
Last-Ply failure	•							
Delamination	•			•	•			
Composite Cure Simulation	◻							

STRUCTURES

	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM		
Structural Solver Capabilities								
Linear Static	•	•	•			•		
Nonlinear Static	•	•	•			•		
Pre-Stress effects, Linear perturbation	•	•	•	▲	▲			
Nonlinear Geometry	•	•	•	•	•	•		
Buckling - Linear Eigenvalue	•	•	•					
Buckling - Nonlinear Post Buckling Behavior	•	•	•		•	•		
Buckling - Nonlinear Post Buckling Behavior - Arc Length	•	•						
Steady State Analysis Applied to a Transient Condition	•							
Advanced Wave Loading	•							
Topology Optimization								
Structural optimization	•	•	•			•		
Modal optimization	•	•	•			•		
Thermal Loads	•	•	•					
Inertial Loads	•	•	•					
Optimized Design Validation	•	•	•			•		
Manufacturing Constraints	•	•	•			▲		
Stress Constraints	•	•	•			•		
Symmetry	•	•	•			•		
Lattice Optimization	□							
Overhang/Additive constraints	□							
Multi Analysis								
Submodeling	•	•	•					
Data Mapping	•	•	•			•		
Multiphysics Data Mapping	•	•						
Initial State	•	•		•	•			
Advanced Multi-Stage 2D to 3D Analysis	•	•						

STRUCTURES

	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM		
Vibrations								
Modal	•	•	•			•		
Modal - Pre-Stressed	•	•	•			•		
Modal - Damped/Unsymmetric	•	•						
Transient - Mode-Superposition	•	•						
Harmonic - Mode-Superposition	•	•						
Harmonic - Full	•	•						
Spectrum	•	•						
Random Vibration	•	•				•		
Mistuning	•	•						
Rotordynamics	•	•						
Modal Acoustic	•							
Harmonic Acoustic	•							
Nonlinear Transient Dynamics								
Rigid Body Mechanisms	•	•						
Rigid Body Dynamics with CMS I Components for Flexible Bodies	•							
Full Transient	•	•		•	•			
CMS with Substructuring	•							

STRUCTURES

	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM		
Explicit Dynamics								
FE (Lagrange) Solver	•			•	•			
Euler Solvers	▲			•				
Meshless Solvers				•				
Implicit-Explicit Deformations	•			•	•			
Implicit-Explicit Material States	•			•				
Fluid-Structure Interaction (FSI)	•			•				
Mass Scaling	•			•	•			
Natural Fragmentation	•			•				
Erosion Based on Multiple Criteria	•			•	•			
De-Zoning				•	•			
Part Activation and Deactivation (Multi Stage Analysis)				•				
Remapping in Space				•				
Remapping Solution Methods				•				
Durability								
Stress-Life (SN)	•	•	•			•		
Strain-Life (EN)	•	•	•			•		
Dang Van	□ ¹	□ ¹	□ ¹					
Safety Factor	•	•	•			•		
Adhesive Bond	□ ¹	□ ¹	□ ¹					
Crack Growth Linear Fracture Mechanics	□ ¹	□ ¹	□ ¹					
Seam Weld	□ ¹	□ ¹	□ ¹					
Spot Weld	□ ¹	□ ¹	□ ¹					
Thermo-Mechanical Fatigue	□ ¹	□ ¹	□ ¹					
Vibration Fatigue	□ ¹	□ ¹	□ ¹					
Virtual Strain Gauge Correlation	□ ¹	□ ¹	□ ¹					
Python Scripting Customization	□ ¹	□ ¹	□ ¹					

• = Fully Support ▲ = Limited Capability □ = Requires more than 1 product

STRUCTURES

	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM		
Wave Hydrodynamics								
Diffraction and Radiation	•							
Frequency & Time Domain Motions Analysis	•							
Moorings, Joints & Tethers	•							
Load Transfer to Structural Analysis	•							
Thermal								
Steady State Thermal	•	•	•			•		
Transient Thermal	•	•	•			•		
Conduction	•	•	•	•	•	•		
Convection	•	•	•			•		
Radiation to Space	•	•	•			•		
Radiation - Surface to Surface	•	•	•					
Phase Change	•	•	•	•	•			
Thermal Analysis of Layered Shells and Solids	•	•						
Additional Physics								
1-D Thermal-flow	•	•	•					
1-D Coupled-field Circuits	•							
1-D Electromechanical Transducer	•							
MEMS ROM	•							
Piezoelectric	•							
Piezoresistive	•							
Electroelastic	•							
Electromagnetic	•					▲		
Vibro-acoustics	•							
Electro-Migration	•							
Diffusion-Pore-Fluid	•							
Diffusion-Thermal Structural-Electric	•							
Structural-Thermal-Electric-Magnetic	•					▲		
1-Way Fluid-Structure Interaction	◻	◻	◻			•		
2-Way Fluid-Structure Interaction	◻							

STRUCTURES

	MECHANICAL ENTERPRISE	MECHANICAL PREMIUM	MECHANICAL PRO	AUTODYN	LS-DYNA	AIM		
Optimization								
DesignXplorer Included	•	•	•	□	□	•		
Parameters	•	•	•	•	•	•		
Design Point Studies	•	•	•	•	•	•		
Correlation Analysis	•	•	•	•		•		
Design of Experiments	•	•	•	•		•		
Sensitivity Analysis	•	•	•	•		•		
Goal Driven Optimization	•	•	•	•		•		
Six Sigma Analysis	•	•	•	•		•		
Miscellaneous and Usability								
ANSYS SpaceClaim	•	□	□	□	□	•		
ANSYS Customization Suite (ACS)	•	□	□	□	□	•		
Support ACT Extensions	•	•	•	•	•	•		
Command Snippet Support	•	•	•			•		
Batch run capability	•	•	•	•	•	•		
External Code Interfaces	•	•		•	•			
On the Fly Post Processing	•	•			•			
CDB and 3rd Party FE Model Import	•	•			•			
HPC - Structures								
Default Number of Cores	4 (DMP + SMP) MAPDL 4 for Explicit 4 for RBD MAPDL 4 for AQWA	4 (DMP + SMP)	4 (DMP + SMP)	1	1	4 (DMP + SMP) MAPDL		
Parallel Solving on Local PC	•	•	•	•	•	•		
Parallel Solving on Cluster	•	•	•	•	•			
GPU Acceleration	□ ⁶ MAPDL - Yes Explicit - No RBD - No Aqwa - No	□ ⁶	□ ⁶					
Parallel Solving Over Cloud Launched from Desktop	MAPDL - Yes Explicit - No RBD - No Aqwa - No							

1 = ANSYS nCode DesignLife Products
 2 = ANSYS Fluent
 3 = ANSYS DesignXplorer
 4 = ANSYS SpaceClaim
 5 = ANSYS Customization Suite (ACS)
 6 = ANSYS HPC, ANSYS HPC Pack or ANSYS HPC Workgroup

DMP = Distributed-memory parallel
 SMP = Shared-memory parallel
 MAPDL = Mechanical APDL
 Explicit = Autodyn
 RBD = Rigid Body Dynamics
 Aqwa = Aqwa

FLUIDS

	FLUENT	CFX	POLYFLOW	FORTE	FENSAP-ICE	AIM	CHEMKIN ENTERPRISE
General Solver Capabilities							
Comprehensive Inlet and Outlet Conditions	•	•	•	•	•	•	•
Steady-State Flow	•	•	•	•	•	•	•
Transient Flow	•	•	•	•	•	•	•
2D and 3D Flow	•	▲	•	▲	•	▲	▲
Reduced Order Models (ROM)	•						•
Time Dependent Boundary Conditions	•	•	•	•	•	▲	•
Customizable Materials Library	•	•	•	•	•	•	•
Fan Model	•	•			•		
Periodic domains	•	•	•	•	•	•	•
Flow-Driven Solid Motion (6DOF)	•	•			•		
Pressure-Based Coupled Solver	•	•	•	•	•	•	•
Density-Based Coupled Solver	•						•
Dynamic/Moving-Deforming Mesh	•	•	•	•	•		•
Overset Mesh	•						
Immersed-Solid/MST Method for Moving Parts		•	•		•		
Automatic On-the-Fly Mesh Generation with Dynamic Refinement	•			•			•
Dynamic Solution-Adaptive Mesh Refinement	•	•		•	▲		•
Polyhedral Unstructured Solution-Adaptive Mesh Refinement	•						
Single Phase, Non-Reacting Flows							
Incompressible Flow	•	•	•			•	•
Compressible Flow	•	•		•	•	•	•
Porous Media	•	•	•				
Non-Newtonian Viscosity	•	•	•				
Turbulence - Isotropic	•	•	•	•	•	•	•
Turbulence - Anisotropic (RSM)	•	•					
Turbulence - Unsteady (LES/SAS/DES)	•	•					•
Turbulence - Laminar/Turbulent Transition	•	•			•	•	•
Flow Pathlines (Massless)	•	•	•			•	
Fan Model	•	•			•		
Acoustics (Source Export)	•	•			•		
Acoustics (Noise Prediction)	•	▲					

FLUIDS

	FLUENT	CFX	POLYFLOW	FORTE	FENSAP-ICE	AIM	CHEMKIN ENTERPRISE
Heat Transfer							
Natural Convection	•	•			•	•	•
Conduction & Conjugate Heat Transfer	•	•			•	•	•
Shell Conduction (Including Multi-Layer Model)	•						
Internal Radiation - Participating Media	•	•	•		•		•
Internal Radiation - Transparent Media	•	•					•
External Radiation	•	•				•	•
Solar Radiation & Load	•	•					
Simplified Heat Exchanger Model	•						
Non-equilibrium Thermal Model	•						
Prorous Media	•						
Particles Flows (Multiphase)							
Coupled Discrete Phase Modeling Including Thin Wall Films	•	•		•	•	▲	•
Macroscopic Particle Model	•					▲	
Inert Particle Tracking (with Mass)	•	•				▲	
Liquid Droplet (Incl. Evaporation)	•	•		•	•		•
Combusting Particles	•	•		•			•
Multicomponent Droplets	•	•		•	•		•
Discrete Element Model (DEM)	•						
Break-Up And Coalescence	•	•		•	•		•
Erosion	•	•					
Free Surface Flows (Multiphase)							
Implicit VOF	•	•	•				
Explicit VOF	•	•	•				
Coupled Level Set/VOF	•	•			•		
VOF to DPM Spray Model	•						
Open Channel Flow And Wave	•	•					
Surface Tension	•	•		•	•		
Phase Change	•	•		•	•		
Cavitation	•	•		•	•		
Cavitation Where Multiple Fluids and Non-Condensing Gases Are Present	•						

FLUIDS

	FLUENT	CFX	POLYFLOW	FORTE	FENSAP-ICE	AIM	CHEMKIN ENTERPRISE
Dispersed Multiphase Flows (Multiphase)							
Mixture Fraction	•	•					
Eulerian Model including Thin Wall Films	•	•		•	•		
Boiling Model	•	•		•			•
Surface Tension	•	•		•			•
Phase Change	•	•		•	•		•
Drag And Lift	•	•		•	•		•
Wall Lubrication	•	•		•			•
Heat And Mass Transfer	•	•		•	•		•
Population Balance	•	•		•			•
Reactions Between Phases	•	•		•			•
Granular Model for Dense Bed of Solids	•	•					
Dense Particulate Coupling (DDPM)	•	•					
Reacting Flows							
Species Transport	•	•	•	•			•
Non-Premixed Combustion	•	•		•			•
Premixed Combustion	•	•		•			•
Partially Premixed Combustion	•	•		•			•
Composition PDF Transport	•	•					
Finite Rate Chemistry	•	•	•	•			•
Pollutants and Soot Modeling	•	•		•			•
Sparse Chemistry Solver with Dynamic Cell Clustering and Dynamic Adaptive Chemistry	•			•			•
Ability to Use Model Fuel Library Mechanisms	•			•			•
Flame-Speed from Fuel-Component Library	•			•			•
DPIK Spark-Ignition Model				•			•
Flame-Propagation Using Level-Set Method (G-Equation)				•			•
Internal Combustion Engine Specific Solution	•	•		•			•
0-D/1-D/2-D Reactor Models and Reactor Networks							•
Plasma Reactions							•
Comprehensive Surface-Kinetics	•						•
Chemical and Phase Equilibrium	•						•
Flamelet Table Generation	•						•
Flamespeed and Ignition Table Generation							•
Reaction Sensitivity, Uncertainty and Path Analysis							•
Surrogate Blend Optimizer							•
Mechanism Reduction							•

FLUIDS

	FLUENT	CFX	POLYFLOW	FORTE	FENSAP-ICE	AIM	CHEMKIN ENTERPRISE
Turbomachinery							
MRF/Frozen-Rotor	•	•					
Sliding-Mesh/Stage	•	•					
Transient Blade Row		•					
Pitch Change		•					
Time Transformation		•					
Fourier Transformation		•					
Harmonic Analysis		•					
Blade Flutter Analysis		•					
Forced Response Analysis		•					
Flank Milled Blades		•					
In-Flight Icing							
Simulates Droplet Sizes					•		
Simulates Ice Growth and Performs Visibility Studies					•		
Models Heat Transfer Anti- and De-icing Heat Loads					•		
Rotating Frame of Reference for the Analysis of Turbomachines, Rotors and Propellers					•		
Model Ice Accretion at Engine Face (Fan and IGV) and within Any Number of Successive Compressor Stages					▲		
Aerodynamic Degradation (CFD) Meets the Requirements of Appendix C, Appendix D (Ice Crystals) and Appendix O (SLD)					•		

FLUIDS

	FLUENT	CFX	POLYFLOW	FORTE	FENSAP-ICE	AIM	CHEMKIN ENTERPRISE
Optimization							
Parameters	•	•	•			•	•
Design Point Studies	•	•	•			•	•
Correlation Analysis	•	•	•			•	
Design of Experiments	•	•	•			•	
Sensitivity Analysis	•	•	•			•	•
Goal Driven Optimization	•	•	•			•	
Six Sigma Analysis	•	•	•			•	
Adjoint Solver for Shape Optimization	•						
Adjoint Solver Supports Rotating Reference Frames & Conjugate Heat Transfer	•						
Multi-Objective-Constrained Optimization	•						
Mesh Morphing (RBF Morph)	◻						
High Rheology Material							
Viscoelasticity			•				
Specialty Extrusion Models			•			▲	
Specialty Blow Molding Models			•			▲	
Specialty Fiber Spinning Models	•						
HPC – Fluids							
Parallel Solving on Local PC Option	•	•	•	•	•	•	•
Parallel Solving Over Network Option	•	•	•	•	•	•	
Parallel Solving Over Cloud Launched from Desktop	•						
GPU Support	•		•				
Pre and Post Processing							
Photo Realistic Rendering	•	•	•	•	•		•
SpaceClaim Direct Modeler	•	•	•	•	•	•	•
Compare Multiple Runs, Datasets, Physics, Graphs in a Single Window	•	•	•	•	•		•

FLUIDS

	FLUENT	CFX	POLYFLOW	FORTE	FENSAP-ICE	AIM	CHEMKIN ENTERPRISE
Multiphysics							
Advanced, Automated Data Exchange	•	•	•		•	•	
Accurate Data Interpolation Between Dissimilar Meshes	•	•			•	•	
Drag-n-Drop Multiphysics	•	•	•				
Direct Coupling Between Physics	•	•				•	
Collaborative Workflows	•	•				•	
Fully Managed Co-Simulation	•	•					
Flexible Solver Coupling Options	•	•			•		
Fluid-Structure Interaction							
Force Induced Motion/Deformation	□	□	•			•	
Fluid Thermal Deformation	□	□				•	
Electro-Thermal Interaction							
Convection Cooled Electronics	•	•					
Conduction Cooled Electronics	•	•					
High Frequency Thermal Management	•	•					
Electromechanical Thermal Management	•	•					
Other Coupled Interactions							
Aero-Vibro Acoustics	•						
Acoustics-Structural	•	•					
Fluid Magnetohydrodynamics	•	•					
Ease of Use and Productivity							
Support ACT Extensions	•						
Mosaic-Enabled Meshing Technology	•						
Task-Based Workflow - Watertight Geometries	•						
Task-Based Workflow - Fault Tolerant (Beta)	•						
Directly Enter Expressions	•	•				•	

ELECTRONICS

	MAXWELL	HFSS	SIwave	Q3D EXTRACTOR	ICEPAK	AIM		
Low Frequency Electromagnetics								
Electrostatics	•					•		
AC Conduction	•					•		
DC Conduction	•					•		
Magnetostatics	•					•		
Adaptive Field Mesh	•	•	•	•		•		
AC Harmonic Magnetic	•					•		
Electric Transient	•							
Magnetic Transient								
Translational Motion	•							
Fully Automatic Symmetrical Mesh Generation	•							
Rotational Motion	•							
Non-Cylindrical Motion	•							
Advanced Embedded Circuit Coupling	•							
Circuit Coupling with Adaptive Time Stepping	•							
Direct and Iterative Matrix Solvers	•							
Advanced Magnetic Modeling								
Vector Hysteresis Modeling	•							
Hysteresis Modeling for Anisotropic Material	•							
Frequency Dependent Reduced Order Models	•							
Equivalent Model Extraction (Linear-Motion, Rotational-Motion, No-Motion)	•							
Functional Magnetization Direction	•							
Magnetization/De-magnetization Modeling	•							
Manufacturing Dependent Core Loss Models	•							
Noise - Vibration Modeling	□							
Temperature De-magnetization Modeling	•							
Core Loss computation	•					•		
Lamination Modeling	•							
Magnetostriction and Magnetoelastic Modeling	•							
Hardware in the Loop modeling	•							
Integrated Motor Synthesis and Design Kit	•							
Integrated Planar Magnetics Synthesis and Design Kit	•							

ELECTRONICS

	MAXWELL	HFSS	SIwave	Q3D EXTRACTOR	ICEPAK	AIM		
High Frequency Electromagnetics								
Fully Automated Adaptive Mesh Refinement		•						
Multi-Frequency Broadband Adaptive Meshing		•						
Frequency Domain Finite Element (FEM) Analysis		•						
Frequency Domain Integral Equation (MoM) Analysis		•						
Time Domain FEM Analysis		•						
FEM Eigenmode Analysis		•						
MoM Characteristic Mode Analysis		•						
Physical Optics (PO) Analysis		□						
Shooting and Bouncing Ray+ (SBR+) Analysis		□						
Physical Theory of Diffraction (PTD) correction for SBR		□						
Uniform Theory of Diffraction (UTD) Correction for SBR		□						
Visual Ray Tracing for SBR+ Analysis		□						
Domain Decomposition Method (DDM) for Frequency Domain FEM Analysis		•						
Hybrid Finite Element/Integral Equation Analysis		•						
UI Coupled Finite Element and/or IE with SBR+ Analysis		•						
Modal Wave Port Excitation		•						
Terminal Wave Port Excitations		•						
Lumped, Voltage and Current Excitations		•						
Parametric Antenna Excitations for SBR+		•						
Floquet Excitations		•						
Incident Wave Excitation		•						
Magnetic Ferrite Bias Excitation		•						
Perfect Electric and Magnetic Boundary		•						
Finite Conductivity Boundary		•						
Lumped RLC Boundary		•						
Symmetry Boundary		•						
Periodic Boundary		•						
Continued on next page								

ELECTRONICS

	MAXWELL	HFSS	SIwave	Q3D EXTRACTOR	ICEPAK	AIM		
High Frequency Electromagnetics (continued)								
Frequency Dependant Materials		•						
Higher and Mixed Order Elements		•						
Curvilinear Element Mesh Correction		•						
S,Y,Z Matrix Results		•						
E, H, J, P Field Results		•						
Direct and Iterative Matrix Solvers		•						
Antenna Parameter Calculation		•						
Infinite and Finite Antenna Array Calculations		•						
Radar Cross Section Calculation		•						
FSS, EBG and Metamaterial Calculation		•						
Specific Absorption Rate Calculation		•						
EMI/EMC Calculation		•						
System Level EMI and RFI Analysis		•						
Linear Circuit Analysis with EM Dynamic Link		•						
Integrated Antenna Synthesis and Design Kit		•						
3D Component Libraries with User Controlled Parametrics		•						
3D Component with Encryption Creation		•						
3D Component with Encryption Utilization		•						

ELECTRONICS

	MAXWELL	HFSS	SIwave	Q3D EXTRACTOR	ICEPAK	AIM		
Power and Signal Integrity Board Simulation Capabilities								
Electronics Desktop 3D Layout GUI		•	•		•			
ECAD Translation (Altium, Cadence, Mentor, Pulsonix, & Zuken)		•	•					
MCAD (.sat) Generation from ECAD		•	•					
Lead Frame Editor		•	•					
DC Voltage, Current and Power Analysis for PKG/PCB			•					
DC Joule Heating with ANSYS Icepak			•	•	•			
Passive Excitation Plane Resonance Analysis			•					
Driven Excitation Plane Resonance Analysis			•					
Automated Decoupling Analysis			•					
Capacitor Loop Inductance Analysis			•					
AC SYZ Analysis - PI, SI, & EMI			•					
Dynamically Linked Electromagnetic Field Solvers			•					
Chip, Package, PCB Analysis (CPM)		•	•					
Near-Field EMI Analysis			•					
Far-Field EMI Analysis			•					
Characteristic Impedance (Zo) PKG/PCB Scan			•					
Full PCB/PKG Cross-talk Scanning			•					
TDR Analysis		•	•	•				
Transient IBIS Circuit Analysis		•	•					
SerDes IBIS-AMI Circuit Analysis			•					
Macro-Modeling (Network Data Explorer)			•					
Steady State AC (LNA) Analysis			•					
Virtual Compliance - DDRx, GDDRx, & LPDDRx			•					
Synopsys HSPICE Integration			•					
Cadence PSPICE Support			•					
Electromagnetically Circuit Driven Field Solvers		•	•					

ELECTRONICS

	MAXWELL	HFSS	SIwave	Q3D EXTRACTOR	ICEPAK	AIM		
RLCG Parasitic Extraction								
DCRL, ACRL & CG Solver				•				
IC Packaging RLCG IBIS Extraction for Signals & Power				•				
Touchpanel RLCG Unit Cell Extraction				•				
Adaptive Meshing for Accurate Extraction				•				
Bus Bar RLCG Extraction				•				
Power Inverter & Converter Component Extraction				•				
Specialized Thin Plane Solver for Touchpanel Extraction				•				
3D Component Library		•		•				
Reduced RLCG Matrix Operations				•				
SPICE equivalent Modeling Export				•				
DCRL & ACRL Joule Heating Analysis with Icepak				•				
Macro-Modeling (Network Data Explorer)				•	•			
2D Transmission Line Modeling Toolkit				•				
2D Cable Modeling Toolkit				•				
Electronics Cooling								
Multi-Mode Heat Transfer					•			
Steady-State and Transient					•			
CFD Analysis					•			
Turbulent Heat Transfer					•			
Multiple-Fluid Analysis					•			
Species Transport					•			
Solar Loading					•			
Reduced Order Flow and Thermal					•			
Network Modeling					•			
Joule Heating Analysis	□	□	□	□	•			
Thermo-electric Cooler Modeling					•			
Thermostat Modeling					•			
Package Characterization					•			
Data Center Modeling					•			

ELECTRONICS

	MAXWELL	HFSS	SIwave	Q3D EXTRACTOR	ICEPAK	AIM		
HPC for Electronics								
GPU Support	□	□						
HPC Accelerated Frequency Sweeps		•	•					
HPC Distributed Hybrid Solving		•						
HPC Enabled Domain Decomposition Method	•	•						
HPC Time Decomposition Method	•							
HPC Enabled Multi-port Excitation Acceleration		•						
HPC Acceleration for DCRL, ACRL and CG				•				
HPC Enabled Parallel Processing	•	•		•	•			
SYSTEMS MODELING - ELECTRONIC PRODUCTS								
System Modeling for Power Electronics								
Circuit Simulation	•	•	•	•	•			
Block Diagram Simulation	•	•	•	•	•			
State Machine Simulation	•	•	•	•	•			
VHDL-AMS Simulation	•	•	•	•	•			
Integrated Graphical Modeling Environment	•	•	•	•	•			
Power Electronics Component Libraries	•	•	•	•	•			
Reduced Order Modeling	•	•	•	•	•			
Power Electronic Device and Module Characterization	•	•	•	•	•			
Co-Simulation with MathWorks Simulink	•	•	•	•	•			
System Modeling for RF/Microwave								
Radio Frequency Interference (RFI) System Solver		□						
Electromagnetic Interference System Solver		□						
RF Link Budget Analysis		□						
RF Co-Site and Antenna Coexistence Analysis		□						
Automated Diagnostics for Rapid Root-Cause Analysis		□						
RF Component Library		□						
Wireless Propagation Models		□						
Multi-Fidelity Parametric Radio Models		□						
Antenna-to-Antenna Coupling Models		□						

ELECTRONICS

	MAXWELL	HFSS	SIwave	Q3D EXTRACTOR	ICEPAK	AIM		
System Modeling for SI/PI								
SerDes Channel Modeling - IBIS-AMI, QuickEye and VerifEye		□	•					
Multi-Drop & Parallel Bus Modeling - IBIS, HSPICE, Spectre, PSPICE, and Nexxim Transient		□	•					
Network Data Exploration		•	•	•				
TDR Analysis		□	•					
Steady State AC (LNA) Analysis		□	•					
Virtual Compliance - DDRx, GDDRx, & LPDDRx		□	•					
MULTIPHYSICS								
Platform Technologies								
Advanced, Automated Data Exchange	•	•		•	•			
Accurate Data Interpolation Between	•	•		•	•			
Dissimilar Meshes	•	•		•	•			
Drag-n-Drop Multiphysics	•	•		•	•			
Direct Coupling Between Physics	•	•		•	•			
Collaborative Workflows	•	•		•	•			
Fully Managed Co-Simulation	•	•		•	•			
Flexible Solver Coupling Options	•	•		•	•			
Electro-Thermal Interaction								
Convection Cooled Electronics		•			•			
Conduction Cooled Electronics		•			•			
High Frequency Thermal Management		•		•	•			
Electromechanical Thermal Management	•			•	•			
Miscellaneous								
Integrated Windows HPC Support	•	•	•	•	•			
Integrated IBM Spectrum LSF Support	•	•	•	•	•			
Customizable 3rd Party Scheduler Support	•	•	•	•	•			
Support ACT Extensions	▲	▲	▲	▲	▲	▲		

SYSTEMS & EMBEDDED SOFTWARE

	TWIN BUILDER	medini ANALYZE	ARCHITECT	SCADE SUITE	SCADE DISPLAY	VRXPERIENCE		
System Simulation, Validation and Digital Twins								
Integrated Graphical Modeling Environment	•							
Standard Modeling Languages and Exchange Formats	•							
Multi-Domain Systems Modeler	•							
Extensive OD Application-Specific Libraries	•							
3rd Party (1D) Tool Integrations	•							
3D ROM	•							
Embedded Software Integration	•							
Multi-Domain System Simulation	•							
Rapid HMI Prototyping	•							
System Optimization	•							
XIL Integration	•							
IIoT Connectivity	•							
Digital Twin Runtime Deployment	•							
Functional Safety Analysis								
Safety Concept Modelling		•						
Model Based Safety Analysis		•						
Reliability Prediction and Analysis		•						
Traceability and Validation Teamwork		•						
Integration into Engineering Environment		•						
Customization and Process Adaption		•						
ANSYS Product Integration		•						
Reporting and Documentation		•						

SYSTEMS & EMBEDDED SOFTWARE

	TWIN BUILDER	medini ANALYZE	ARCHITECT	SCADE SUITE	SCADE DISPLAY	VRXPERIENCE		
Model-based Systems Engineering								
Model-Based System Design			▲	▲				
Functional Decomposition			▲	▲				
Architecture Decomposition			•	•				
Allocation of Functions to Components			•	•				
Model Checks			•	•				
Model Diff/Merge			•	•				
System / Software Bi-Directional Sync			•	•				
Model Sharing and IP Protection			•	•				
Model-Based Interface Control Document Production			•	•				
Configurable for Industry Standards (IMA, AUTOSAR, Etc.)			•	•				
Product Configuration for Automotive Developers			•	•				
Embedded Control Software Development								
Data Flow and State Machine Design and Simulation Capabilities				•				
Extensive Set of Libraries Delivered as Design Examples				•				
Simulation Capabilities				•				
Record and Playback Scenarios				•				
Plant Model Co-Simulation Including FMI				•				
Coverage Analysis For Requirements Based Tests				•				
Formal Verification				•				
Timing And Stack Optimization				•				
Worst Case Execution Time Estimates On Target				•				
Verification of Stack Space Requirements				•				
Certified Code Generation for DO-178C, EN 50128, ISO 26262, IEC 61508				•				
Certification Kits For DO-178C, EN50128, ISO 26262, IEC 61508				•				

SYSTEMS & EMBEDDED SOFTWARE

	TWIN BUILDER	medini ANALYZE	ARCHITECT	SCADE SUITE	SCADE DISPLAY	VRXPERIENCE		
Man-Machine Interface Software								
Model-Based Prototyping and Specification of MMIs					•			
Support Of OpenGL, OpenGL SC and OpenGL ES					•			
Font Management					•			
Optimization of Graphical Specifications					•			
Plant Model Co-Simulation Including FMI					•			
Automatic Generation of iOS and Android Projects					•			
Certified Code Generation For DO-178C, EN 50128, ISO 26262, IEC 61508					•			
Certification Kits For DO-178C, EN50128, ISO 26262, IEC 61508					•			
Testing Capabilities					•			
VRXPERIENCE								
Photometry								
Illuminance						•		
Luminance						•		
3D Illuminance						•		
Human Vision								
Glare Simulation						•		
Optical Sensors								
Ground-Truth sensor						•		
Camera Sensor						•		
LiDAR Sensor						▲		
Sensor Fusion						◻		
Head-up Display								
HUD Visualisation						•		

SYSTEMS & EMBEDDED SOFTWARE

	TWIN BUILDER	medini ANALYZE	ARCHITECT	SCADE SUITE	SCADE DISPLAY	VRXPERIENCE		
Driving								
Automatic Driving						•		
Multi-Vehicles						•		
Scenario, Traffic, Vehicle Dynamic, Road Editor (SCANeR)						□		
CarSim & SensoDrive Interface (SCANeR)						□		
Rendering / Simu								
CAD Material & CAD Rendering						•		
SPEOS Results Visualization						•		
Physical Material & Shadics Rendering						•		
Physical Material & Ray-Tracing Rendering						•		
Advanced Physical Material & Progressive/Hybrid Rendering						•		
Headlamp Simulation								
Headlamp performance assessment						•		
Digital Lighting (Matrix Beam, Pixel beam)						•		
IIHS Test						•		
Tracking								
Head Tracking						•		
Finger Tracking						•		
Body Tracking						•		
Manikin						•		
Distributed Rendering								
Workstation						•		
HMD						•		
Powerwall, CAVE						•		

SYSTEMS & EMBEDDED SOFTWARE

	TWIN BUILDER	medini ANALYZE	ARCHITECT	SCADE SUITE	SCADE DISPLAY	VRXPERIENCE		
Experience								
Trigger & Animation						•		
Physics Engine - Collision & Kinematics						•		
Hard & Soft Switches Interaction						•		
Engine / Solver Embedded or Interface								
Variation Engine (Aesthetica)						•		
System Co-Simulation						□		
Sensor Data Fusion Co-Simulation Display Content Co-Simulation						□		
Acoustics Sounds								
Analyze, Listen & Modify (LEA)						•		
Psychoacoustics, Automatic Detection and Separation, Play 3D Sound (LEA)						•		
Engine Sound Design (ASD)						•		
3D Sound for Listening Room and VR (GeneVR)						•		
Interactive Sound for Driving Simulator (GeneCARS)						•		
Measure Sound Perception (JURY)						•		

GEOMETRY

	DESIGN MODELER	SPACECLAIM DESIGN MODELER						
Direct Modeling Technology		•						
Feature Based Modeling Technology	•							
Open Data from All Major CAD Systems	•	•						
Export Data to Neutral File Formats	•	•						
Modify Imported Geometry	•	•						
Defeaturing and Simplification Tools	•	•						
Model Repair	•	•						
Add Parameters for Design Exploration	•	•						
Extract Mid-Surfaces/Shells and Beams	•	•						
Extract Volumes & Create Inner Fluid Domains	•	•						
Extract Outer Air Enclosures	•	•						
Shared Topology for Conformal Meshing	•	•						
Booleans and Slicing	•	•						
Create Weld Bodies	•	•						
Boundary Condition Mapping	•	•						
Scripting	•	•						
Sketching and Editing Tools	•	•						
3D Comparison Tools		•						
Repair and Edit Faceted Data		•						
Icepak Integration	•	•						
Reverse Engineering Faceted Data		•						

DESIGN TOOLS

	DISCOVERY ESSENTIALS	DISCOVERY STANDARD	DISCOVERY ULTIMATE					
Structural								
Static Structural Analysis		•	•					
Modal Analysis		•	•					
Pre-Stressed Modal Analysis			•					
Random Vibration			•					
Shells, Springs, Point Masses			•					
Spatially Varying Loads			•					
Nonlinear Contact & Joints			•					
Pre-tension Bolts & Multi-step Analysis			•					
Basic Plasticity			•					
Large Deformation			•					
Fatigue Analysis			•					
Topology Optimization		•	•					
Fluid								
Steady-State Flow		•	•					
Transient Flow		•	•					
Time-dependent Fluid Conditions			•					
Incompressible Flow			•					
Compressible Flow ¹		▲	•					
Non-Newtonian Fluids			•					
Periodic Domains			•					
Porous Media			•					
Particle Flow			•					
Thermal								
Steady State Thermal		•	•					
Transient Thermal		•	•					
Time Dependent Thermal Conditions			•					
Conduction		•	•					
Convection		•	•					
Radiation to Space			•					

DESIGN TOOLS	DISCOVERY ESSENTIALS	DISCOVERY STANDARD	DISCOVERY ULTIMATE					
Electromagnetics								
DC Conduction			•					
AC Conduction			•					
Electrostatics			•					
Magnetostatics			•					
AC Harmonic Magnetics			•					
Multiphysics								
Thermal-Stress			•					
Fluid-Structure Interaction			•					
Fluid-Solid Thermal (Conjugate Heat Transfer)			•					
Thermal-Electric			•					
Thermal-Electric-Stress			•					
Thermal-Electromagnetic			•					
Thermal-Electromagnetic-Stress			•					
Design & Concept Modeling								
Concept Modeling or Detail Design	•	•	•					
Part/Assembly Creation or Import	•	•	•					
Large Assembly Importing	•	•	•					
2-D Drawings, BOM, Exploded Views	•	•	•					
Geometric Parameterization	•	•	•					
Sheet Metal Design	•	•	•					
Manufacturing								
Repair & Defeature Tools	•	•	•					
Sheet Metal Editing and Unfolding	•	•	•					

DESIGN TOOLS

	DISCOVERY ESSENTIALS	DISCOVERY STANDARD	DISCOVERY ULTIMATE					
3-D Printing²								
Import, Repair, Edit Faceted Data	•	•	•					
Shelling and Infills	•	•	•					
Thickness Eetection	•	•	•					
Reverse Engineering								
Autosurface of Scanned Data	•	•	•					
Build Solid/Surfaces on Scanned Data	•	•	•					
Interfaces and Add-ons								
Algorx Momentum ³	•	•	•					
Keyshot Rendering ³	•	•	•					
(1) Discovery Live supports mildly compressible fluid flow up to ~Mach 0.3								
(2) Included with Discovery Standard and Ultimate								
(3) Add-on Module"								

ADDITIVE SOLUTIONS	ADDITIVE PRINT	ADDITIVE SUITE*	MECHANICAL ENTERPRISE					
Topology and Lattice Optimization								
Structural Optimization			•					
Modal Optimization			•					
Thermal Loads			•					
Inertial Loads			•					
Optimized Design Validation			•					
Manufacturing Constraints			•					
Stress Constraints			•					
Symmetry			•					
Lattice Optimization		•	◻					
Overhang/Additive Constraints		•	◻					
Geometry and STL File Handling								
SpaceClaim Direct Modeler	•	•	•					
Workbench Additive								
Nonlinear and Temperature Dependent Material Properties		•						
Thermo-Mechanical Coupled Strain Solution		•						
Native Mechanical Environment		•						
Stress-Based Automatically Generated Supports		•						
Part Distortion & Residual Stress (As-Built)		•						
Part Distortion & Residual Stress After Support Removal		•						
Distortion Compensation		•						
Blade Crash Detection		•						
Identification of High Strain (Crack) Locations		•						
Layer by Layer Stress & Distortion Visualizations		•						
Option to Output Only the Last Layer of the Build or Every Nth Layer		•						
User-Defined Step Option as 1st or Last Sequence Step		•						
Layered Tetrahedral Meshing		•						
Post Build Heat Treatment		•						

ADDITIVE SOLUTIONS	ADDITIVE PRINT	ADDITIVE SUITE*	MECHANICAL ENTERPRISE					
Additive Print								
Nonlinear and Temperature Dependent Material Properties	•	•						
Uniform Assumed Isotropic Strain	•	•						
Scan Pattern Based Anisotropic Strain	•	•						
Thermal Ratcheting Based Anisotropic Strain	•	•						
Desktop & Cloud Stand-Alone Environments	•	•						
Stress-Based Automatically Generated Supports	•	•						
Part Distortion & Residual Stress (As-Built)	•	•						
Part Distortion & Residual Stress After Support Removal	•	•						
Distortion Compensation	•	•						
Blade Crash Detection	•	•						
Identification Of High Strain (Crack) Locations	•	•						
Layer by Layer Stress, Distortion & Blade Crash Visualizations	•	•						
Build File Readers for Multiple AM Machines	•	•						
Auto Queue Multiple Successive Simulations	•	•						
Input Strain Hardening Factor	•	•						
User Defined Support Import	•	•						
Subvoxel Material Density Assignment	•	•						
Additive Science								
Nonlinear and Temperature Dependent Material Properties		•						
Meltpool Dimensions		•						
Detailed Thermal History		▲						
% Porosity		•						
Sensor Measurement Predictions		▲						
* Additive Suite requires a Mechanical Enterprise license								

OPTICAL

	SPEOS							
Photometry								
Intensity	•							
Illuminance	•							
Luminance	•							
3D Illuminance	•							
3D Energy Density	•							
Human Vision								
Dynamic Adaptation	•							
Glare Simulation	•							
Wavelength Range								
UV-FIR (50nm-100µm)	•							
Optical Design								
Parabolic Surface	•							
TIR Lens	•							
Projection Lens	•							
Optical Lens	•							
Optical Surface	•							
Light Guide	•							
Sharp Cut-Off Reflector	•							
Poly-Ellipsoidal Surface	•							
Micro Optical Stripes	•							
Optical Sensors								
Field Of View	•							
Camera Sensor	•							
LiDAR Sensor	•							
Sensor Fusion	•							

OPTICAL

	SPEOS							
Head-up Display								
HUD Optical Analysis	•							
HUD Optical Design	•							
HUD Visualisation	•							
Manufacturing Variation								
Target Specification	•							
Tolerance Study	•							
Solver								
Multi-Threading	•							
Highly Scalable HPC	•							
Add-on Features								
Optimizer	•							
Design of Experiment	•							
Regulation Check	•							
Colorimetry	•							
Light Expert	•							
3D Textures	•							
3D Energy Density	•							
Polarization	•							
Fluorescence	•							
360° view	•							
Sky	•							
Visibility & Legibility	•							
Stray Light Analysis	•							
High Dynamic Range Screen support	•							
Virtual BSDF Bench	•							
Thermic Source	•							
MODTRAN Interface	▲							
Night Vision Goggle	•							